ROHM
SEMICONDUCTOR

◇STRUCTURE   Silicon Monolithic Integrated Circuit

◇PRODUCT   256×8 bit Electrically Erasable PROM

◇PART NUMBER   BU9833GUL-W

◇PHYSICAL DIMENSION   Fig.-1

◇BLOCK DIAGRAM   Fig.-2

◇USE   General purpose

◇FEATURES

- 256 registers × 8 bits serial architecture
- Single power supply (1.7V～5.5V)
- Two wire serial interface
- Self-timed write cycle with automatic erase
- 8 byte Page Write mode
- Low power consumption
  - Write (5V) : 1.2mA (Typ.)
  - Read (5V) : 0.2mA (Typ.)
  - Standby (5V) : 0.1 μA(Typ.)
- DATA security
  - Write protect feature (WP pin)
  - Inhibit to WRITE at low Vcc
- WLCSP6Pin package ------ VCSP50L1
- High reliability fine pattern CMOS technology
- Endurance : 1,000,000 erase/write cycles
- Data retention : 40 years
- Filtered inputs in SCL・SDA for noise suppression
- Initial data FFh in all address

◇ ABSOLUTE MAXIMUM RATING (Ta=25℃)

Parameter	Symbol	Rating		Unit
Supply Voltage	Vcc	−0.3～6.5		V
Power Dissipation	Pd	VCSP50L1	220 *1	mW
Storage Temperature	Tstg	−65～125		℃
Operating Temperature	Topr	−40～85		℃
Terminal Voltage	−	−0.3～Vcc+1.0 *2		V

*1 Degradation is done at 2.2mW/℃ for operation above 25℃.
*2 The max value of Terminal Voltage is not over 6.5V.

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◇RECOMMENDED OPERATING CONDITION

Parameter	Symbol	Rating	Unit
Supply Voltage	V_{CC}	1.7〜5.5	V
Input Voltage	V_{IN}	0〜V_{CC}	V

◇DC OPERATING CHARACTERISTICS (Unless otherwise specified Ta=−40〜85℃、V_{CC}=1.7〜5.5V)

Parameter	Symbol	Specification			Unit	test condition
		min.	typ.	max.		
"H" Input Voltage1	V_{IH1}	0.7V_{CC}	—	V_{CC}+1.0	V	2.5V≦V_{CC}≦5.5V
"L" Input Voltage1	V_{IL1}	−0.3	—	0.3V_{CC}	V	2.5V≦V_{CC}≦5.5V
"H" Input Voltage2	V_{IH2}	0.8V_{CC}	—	V_{CC}+1.0	V	1.8V≦V_{CC}<2.5V
"L" Input Voltage2	V_{IL2}	−0.3	—	0.2V_{CC}	V	1.8V≦V_{CC}<2.5V
"H" Input Voltage3	V_{IH3}	0.9V_{CC}	—	V_{CC}+1.0	V	1.7V≦V_{CC}<1.8V
"L" Input Voltage3	V_{IL3}	−0.3	—	0.1V_{CC}	V	1.7V≦V_{CC}<1.8V
"L" Output Voltage1	V_{OL1}	—	—	0.4	V	I_{OL}=3.0mA, 2.5V≦V_{CC}≦5.5V （SDA）
"L" Output Voltage2	V_{OL2}	—	—	0.2	V	I_{OL}=0.7mA, 1.7V≦V_{CC}<2.5V （SDA）
Input Leakage Current	I_{LI}	−1	—	1	μA	V_{IN}=0V〜V_{CC}
Output Leakage Current	I_{LO}	−1	—	1	μA	V_{OUT}=0V〜V_{CC} （SDA）
Operating Current	I_{CC1}	—	—	2.0	mA	V_{CC}=5.5V,f_{SCL}=400kHz,t_{WR}=5ms Byte Write Page Write
	I_{CC2}	—	—	0.5	mA	V_{CC}=5.5V,f_{SCL}=400kHz Random Read Current Read Sequential Read
Standby Current	I_{SB}	—	—	2.0	μA	V_{CC}=5.5V,SDA,SCL=V_{CC} A0,A1,A2=GND,WP=GND

○ This product is not designed for protection against radioactive rays.

◇MEMORY CELL CHARACTERISTICS （Ta=25℃、V_{CC}=1.7〜5.5V）

Prameter		Specification			Unit
		Min.	Typ.	Max.	
Write/Erase Cycle	*1	1,000,000	–	–	Cycles
Data Retention	*1	40	–	–	Years

*1 Not 100% TESTED

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/PIN MARK

Product Name：BU9833GUL-W

9833

1.50 ± 0.1

LOT NO.

1.27 ± 0.1

0.10 ± 0.05

0.55MAX

S

0.08 S

$6-\phi0.25\pm0.05$

0.05 A B

0.25 ± 0.1

$(\phi0.15)$ INDEX POST

C

B

A

A

B

$P=0.5\times2$

0.385 ± 0.1 0.5

1   2
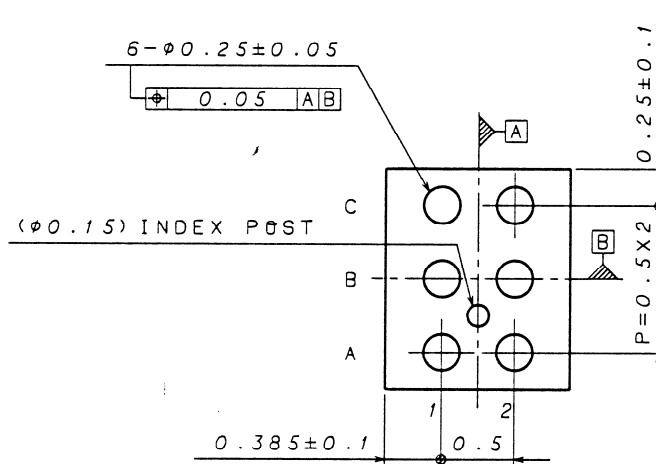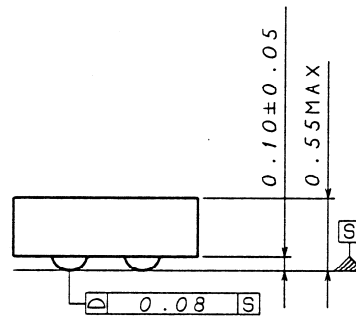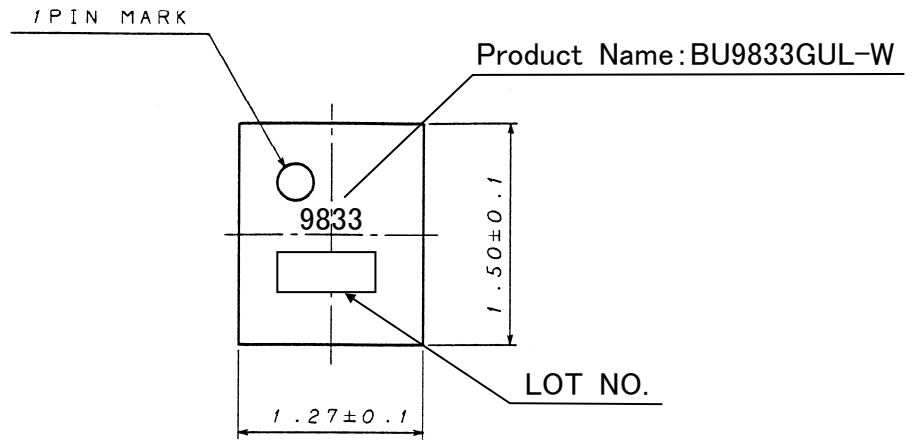
(UNIT：mm)

Drawing No：EX912-5004

Fig.-1 PHYSICAL DIMENSION （VCSP50L1）（Unit : mm）

◇BLOCK DIAGRAM

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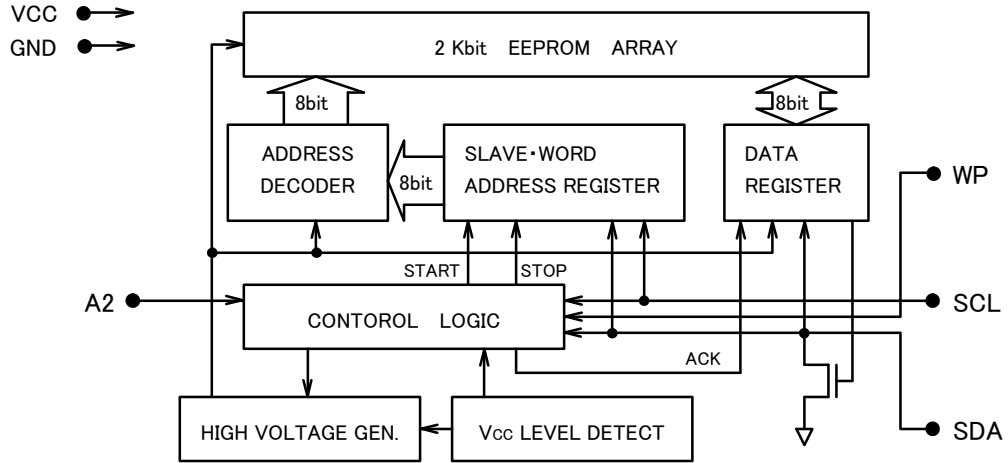
Fig.-2 BLOCK DIAGRAM

◇PIN CONFIGURATION

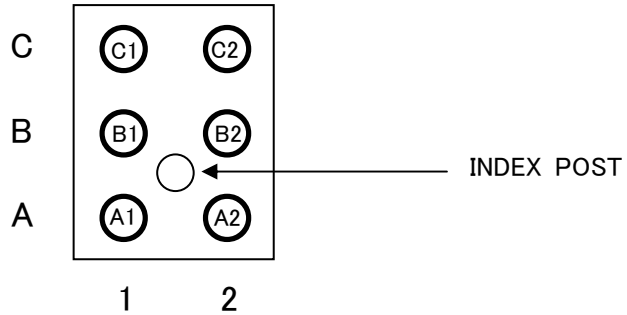Fig.-3 BU9833GUL－W（bottom view）

◇PIN NAME

Land No.	PIN NAME	I/O	FUNCTIONS
C2	Vcc	―	Power Supply
C1	A2	IN	Slave Address Set
B2	WP	IN	Write Protect Input
B1	GND	―	Ground（0V）
A2	SCL	IN	Serial Clock Input
A1	SDA	IN/OUT	Slave and Word Address, Serial Data Input, Serial Data Output *1

*1 An open drain output requires a pull-up resister.

◇AC OPERATING CHARACTERISTICS (Unless otherwise specified Ta=-40～85℃、Vcc=1.7～5.5V)

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| Parameter	Symbol	FAST-MODE 2.5≦Vcc≦5.5V			STANDARD-MODE 1.7≦Vcc≦5.5V			Unit
		Min.	Typ.	Max.	Min.	Typ.	Max.	
Clock Frequency	fSCL	—	—	400	—	—	100	kHz
Data Clock High Period	tHIGH	0.6	—	—	4.0	—	—	μs
Data Clock Low Period	tLOW	1.2	—	—	4.7	—	—	μs
SDA and SCL Rise Time ※1	tR	—	—	0.3	—	—	1.0	μs
SDA and SCL Fall Time ※1	tF	—	—	0.3	—	—	0.3	μs
Start Condition Hold Time	tHD:STA	0.6	—	—	4.0	—	—	μs
Start Condition Setup Time	tSU:STA	0.6	—	—	4.7	—	—	μs
Input Data Hold Time	tHD:DAT	0	—	—	0	—	—	ns
Input Data Setup Time	tSU:DAT	100	—	—	250	—	—	ns
Output Data Delay Time	tPD	0.1	—	0.9	0.2	—	3.5	μs
Output Data Hold Time	tDH	0.1	—	—	0.2	—	—	μs
Stop Condition Setup Time	tSU:STO	0.6	—	—	4.7	—	—	μs
Bus Free Time	tBUF	1.2	—	—	4.7	—	—	μs
Write Cycle Time	tWR	—	—	5	—	—	5	ms
Noise Spike Width（SDA and SCL）	tI	—	—	0.1	—	—	0.1	μs
WP Hold Time	tHD:WP	0	—	—	0	—	—	ns
WP Setup Time	tSU:WP	0.1	—	—	0.1	—	—	μs
WP High Period	tHIGH:WP	1.0	—	—	1.0	—	—	μs

※1：Not 100% TESTED

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◇SYNCHRONOUS DATA TIMING
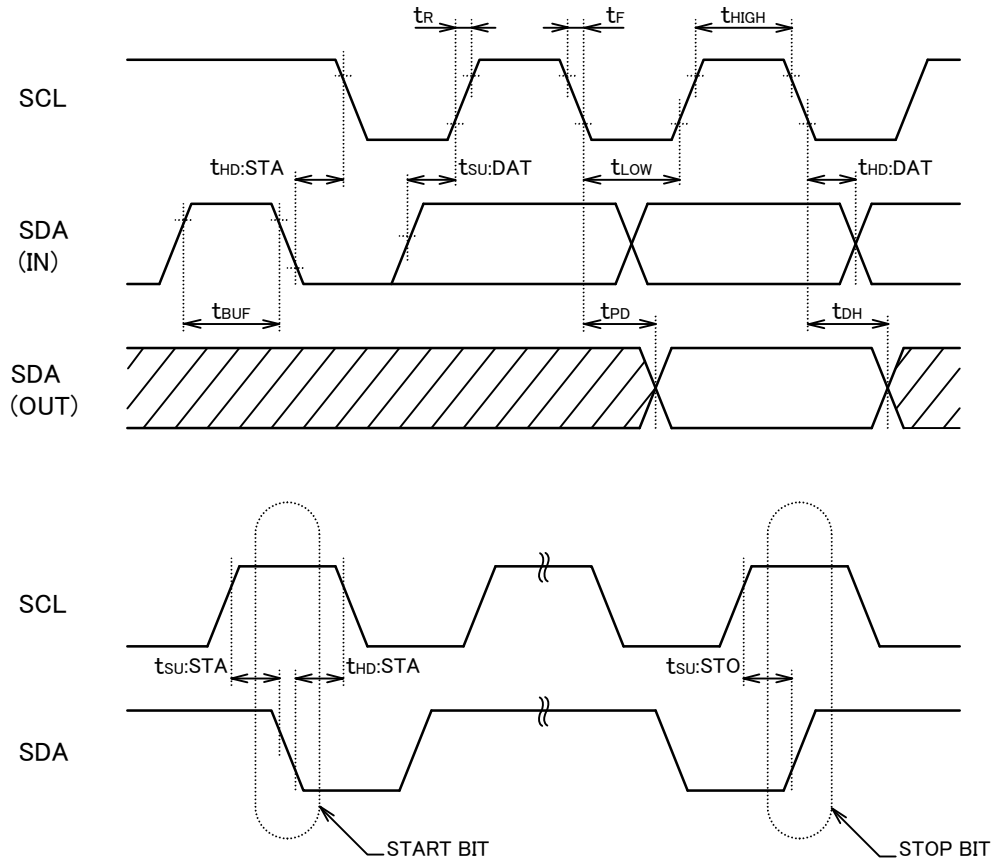
Fig.-4 SYNCHRONOUS DATA TIMING

○SDA data is latched into the chip at the rising edge of SCL clock.
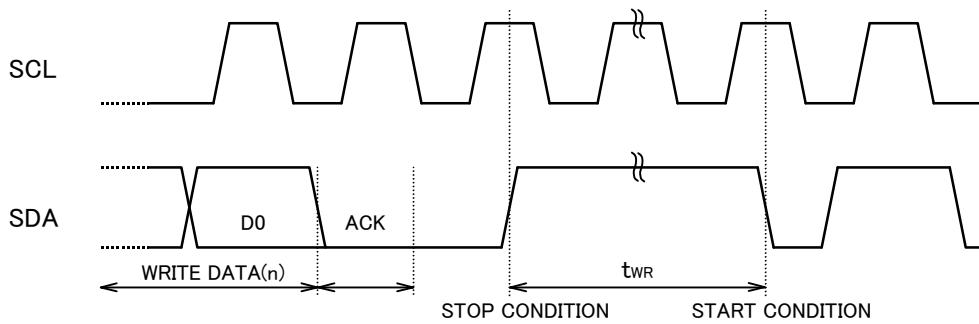○Output date toggles at the falling edge of SCL clock.

◇WRITE CYCLE TIMING
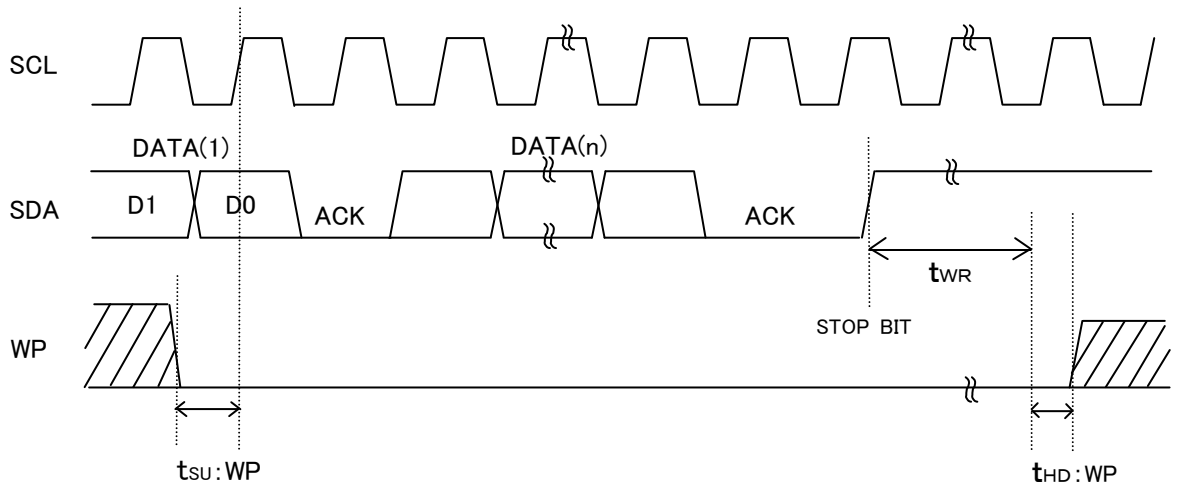

Fig.-5 WRITE CYCLE TIMING

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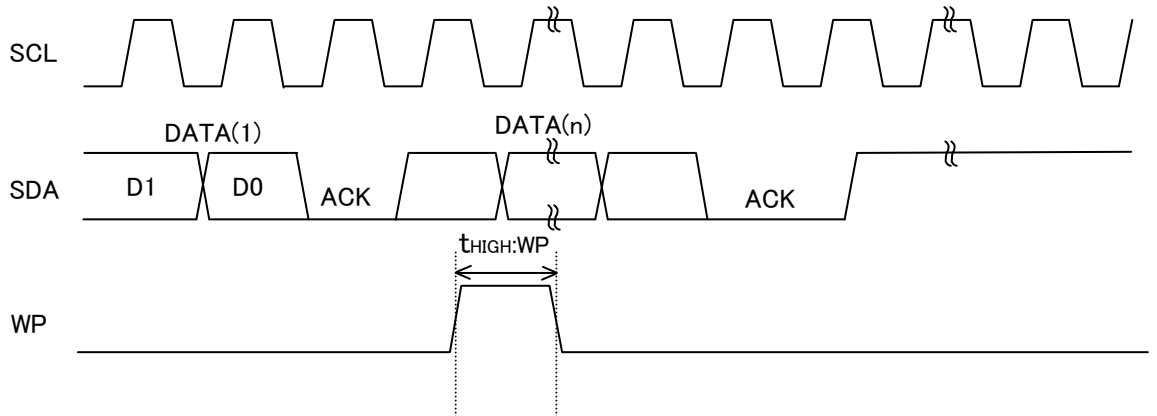◇WP TIMING

Fig-6(a) WP TIMING OF THE WRITE OPERATION

Fig-6(b) WP TIMING OF THE WRITE CANCEL OPERATION

○For the WRITE operation, WP must be "LOW" during the period of time from the rising edge of the clock which takes in D0 of first byte until the end of t_{WR}. (See Fig-6(a))

During this period, WRITE operation is canceled by setting WP "HIGH".(See Fig-6(b))

○In the case of setting WP "HIGH" during t_{WR}, WRITE operation is stopped in the middle and the data of accessing address is not guaranteed. Please write correct data again in the case.

◇DEVICE OPERATION

○START CONDITION (RECOGNITION OF START BIT)
・All commands are proceeded by the start condition, which is a HIGH to LOW transition
  of SDA when SCL is HIGH.
・The device continuously monitors the SDA and SCL lines for the start condition and
   will not respond to any command until this condition has been met.
  (See Fig-4 SYNCHRONOUS DATA TIMING)
○STOP CONDITION (RECOGNITION OF STOP BIT)
・All communications must be terminated by a stop condition, which is a LOW to HIGH
  transition of SDA when SCL is HIGH.
  (See Fig-4 SYNCHRONOUS DATA TIMING)
○NOTICE ABOUT WRITE COMMAND
・In the case that stop condition is not excuted in WRITE mode, transfered data will not
  be written in a memory.
○DEVICE ADDRESSING
・Following a START condition, the master output the slave address to be accessed.
・The most significant four bits of the slave address are the "device type indentifier,"
  For this device it is fixed as "1010."
・The next bit (device address) identify the specified device on the bus.
  The device address is defined by the state of A2 input pin. This IC works
  only when the device address inputted from SDA pin correspond to the state of A2 input
   pin. Using this address scheme, up to two devices may be connected to the bus.
・The last bit of the stream (R/$\overline{W}$ ⋯ READ/$\overline{WRITE}$) determines the operation to be
  performed. When set to "1", a read operation is selected ; when set to "0", a write
  operation is selected.

R/$\overline{W}$ set to "0" ・・・・・・・・ WRITE (including word address input of Random Read)
R/$\overline{W}$ set to "1" ・・・・・・・・ READ

1 0 1 0	A2	0	0	R/$\overline{W}$

○WRITE PROTECT (WP)
  When WP pin set to Vcc(H level), write protect is set for 256 words (all address).
  When WP pin set to GND(L level), enable to write 256 words (all address).
  Either contorol this pin or connect to GND (or Vcc). It is inhibited from being left
  unconnected.

○ACKNOWLEDGE

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・Acknowledge is a software convention used to indicate successful data transfers.
  The transmitter device will release the bus after transmitting eight bits.
(When inputting the slave address in the write or read operation, transmitter is μ-COM.
  When outputting the data in the read operation, it is this device.)
・During the ninth clock cycle, the receiver will pull the SDA line LOW to acknowledge
  that the eight bits of data has been received.
  (When inputting the slave address in the write or read operation, receiver is this
   device. When outputting the data in the read operation, it is μ-COM.)
・The device will respond with an Acknowledge after recognition of a START condition
  and its slave address (8bit).
・In the WRITE mode, the device will respond with an Acknowledge, after the receipt o
  feach subsequent 8-bit word (word address and write data).
・In the READ mode, the device will transmit eight bit of data, release the SDA line,
  and monitor the line for an Acknowledge.
・If an Acknowledge is detected, and no STOP condition is generated by the master,
  the device will continue to transmit the data.
  If an Acknowledge is not detected, the device will terminate further data transmissions
  and await a STOP condition before returning to the standby mode.
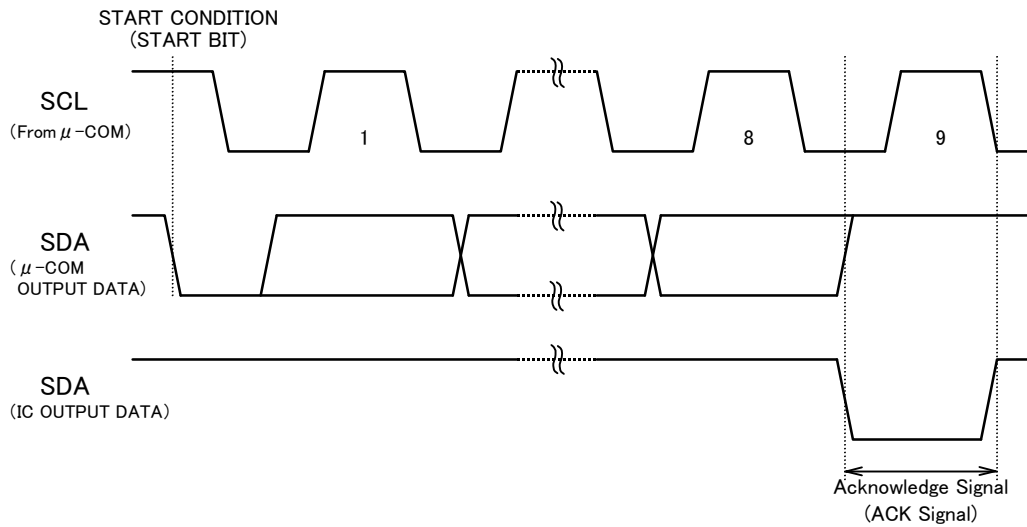 (See Fig-7 ACKNOWLEDGE RESPONSE FROM RECEIVER)
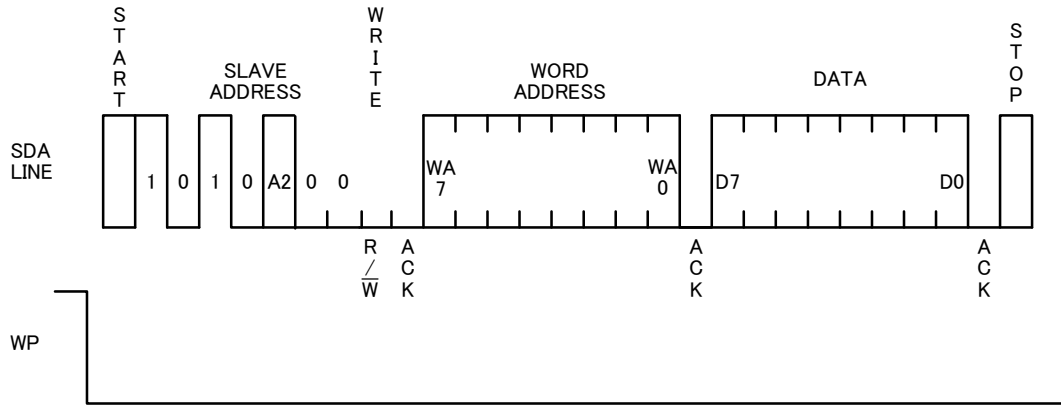
Fig.-7 ACKNOWLEDGE RESPONSE FROM RECEIVER

◇BYTE WRITE

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Fig.-8 BYTE WRITE CYCLE TIMING

○By using this command, the data is programed into the indicated word address.

○When the master generates a STOP condition, the device begins the internal
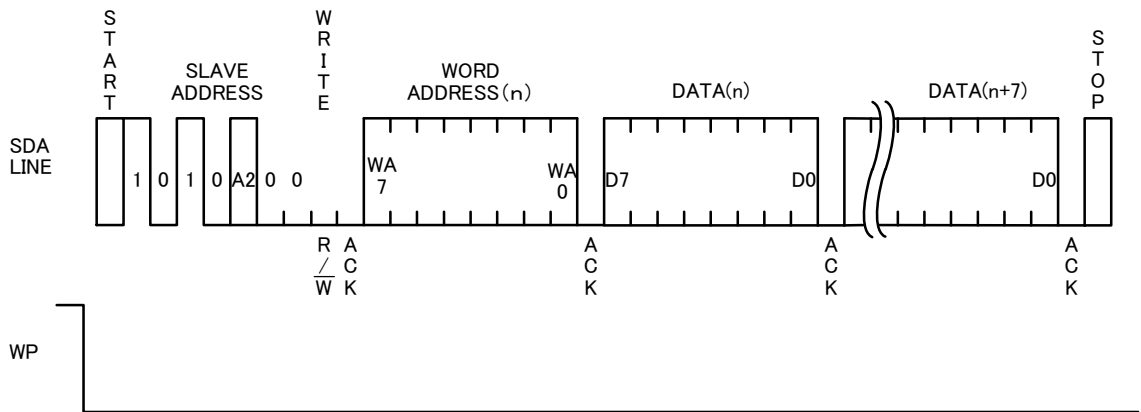write cycle to the nonvolatile memory array.

◇ PAGE WRITE

Fig.-9 PAGE WRITE CYCLE TIMING

○ This device is capable of eight byte Page Write operation.

○ When two or more byte data are inputted, the three low order address bits are internally
incremented by one after the receipt of each word. The five higher order bits of the
address(WA7~WA3) remain constant.

○If the master transmits more than eight words, prior to generating the STOP condition,
the address counter will "roll over," and the previous transmitted data will be overwritten.
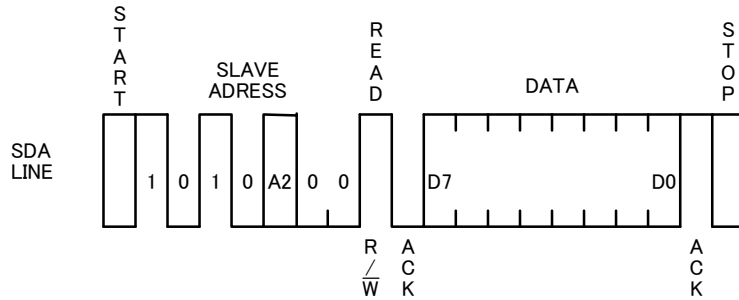
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◇CURRENT READ

Fig.-10 CURRENT READ CYCLE TIMING

○In case that the previous operation is Random or Current Read (which includes Sequential Read respectively), the internal address counter is increased by one from the last accessed address (n). Thus Current Read outputs the data of the next word address (n+1).

If the last command is Byte or Page Write, the internal address counter stays at the last address (n). Thus Current Read outputs the data of the word address (n).

○If an Acknowledge is detected, and no STOP condition is generated by the master (μ-COM), the device will continue to transmit the data. [It can transmit all data (2kbit 256word)]

○If an Acknowledge is not detected, the device will terminate further data transmissions and await a STOP condition before returning to the standby mode.

NOTE) If an Acknowledge is detected with "Low" level, not "High" level, command will become Sequential Read. So the device transmits the next data, Read is not terminated. In the case of terminating Read, input Acknowledge with "High" always, then input stop condition.
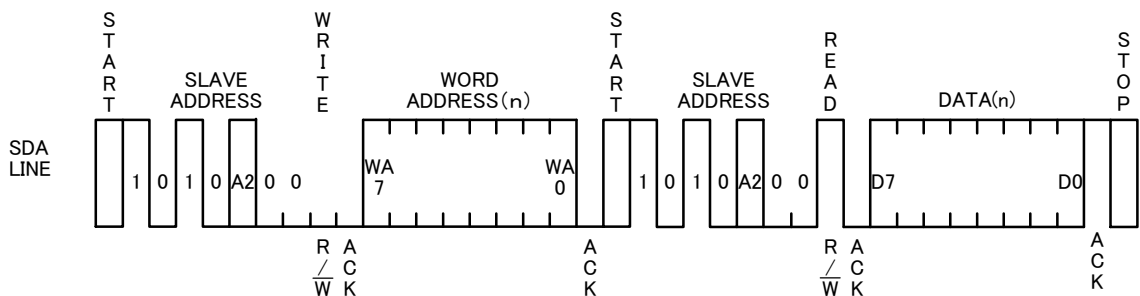
◇RANDOM READ

Fig.-11 RANDOM READ CYCLE TIMING

○Random Read operation allows the master to access any memory location indicated word address.

○If an Acknowledge is detected, and no STOP condition is generated by the master (μ-COM), the device will continue to transmit the data. [It can transmit all data (2kbit 256word)]

○If an Acknowledge is not detected, the device will terminate further data transmissions and await a STOP condition before returning to the standby mode.

NOTE) If an Acknowledge is detected with "Low" level, not "High" level, command will become Sequential Read. So the device transmits the next data, Read is not terminated. In the case of terminating Read, input Acknowledge with "High" always, then input stop condition.
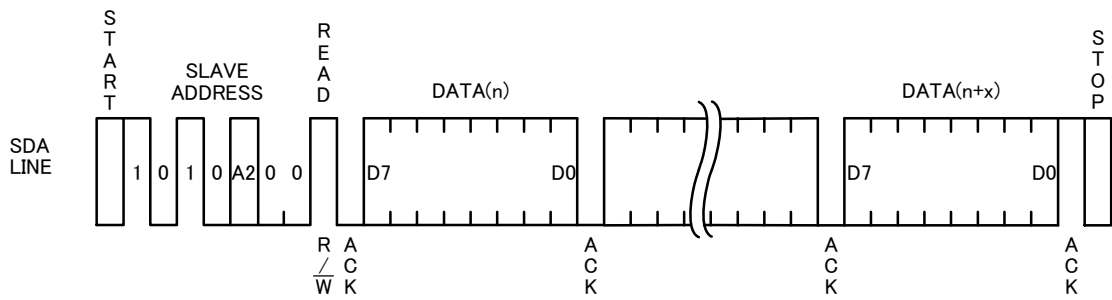
◇SEQENTIAL READ

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Fig.-12 SEQUENTIAL READ CYCLE TIMING
(Current Read)

○If an Acknowledge is detected, and no STOP condition is generated by the master (μ-COM),
  the device will continue to transmit the data. [It can transmit all data (2kbit 256word)]
○If an Acknowledge is not detected, the device will terminate further data transmissions
  and await a STOP condition befere returning to the standby mode.
○The Sequential Read operation can be performed with both Current Read and Random Read.

NOTE) If an Acknowledge is detected with "Low" level, not "High" level, command will become
      Sequential Read. So the device transmits the next data, Read is not terminated. In the
      case of terminating Read, input Acknowledge with "High" always, then input stop condition.

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